# **DB3X316N**

# Silicon epitaxial planar type

For small current rectification

#### ■ Features

- Short reverse recovery time t<sub>rr</sub>
- Low forward voltage V<sub>F</sub>
- Halogen-free / RoHS compliant
   (EU RoHS / UL-94 V-0 / MSL: Level 1 compliant)

#### ■ Marking Symbol: 5J

#### ■ Basic Part Number

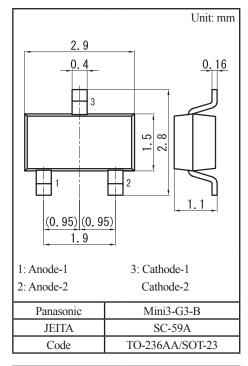
Dual DB2S316 (Common cathode)

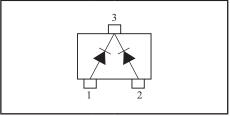
#### Packaging

DB3X316N0L Embossed type (Thermo-compression sealing): 3 000 pcs / reel (standard)

## ■ Absolute Maximum Ratings $T_a = 25$ °C

| Parameter                                    | Symbol         | Rating           | Unit                        |    |  |
|--|----------------|------------------|-----------------------------|----|--|
| Reverse voltage                              |                | $V_R$            | 30                          | V  |  |
| Repetitive peak reverse voltage              |                | V <sub>RRM</sub> | 30                          | V  |  |
| Forward current (Average)                    | Single         | т                | 100                         | mA |  |
|  | Double *1      | $I_{F(AV)}$      | 70                          |    |  |
| Peak forward current                         | Single         | т                | 300                         | mA |  |
|  | Double *1      | $I_{FM}$         | 200                         |    |  |
| Non-repetitive peak forward surge current *2 |                | I <sub>FSM</sub> | 1                           | A  |  |
| Junction temperature                         | T <sub>j</sub> | 125              | °C                          |    |  |
| Operating ambient temperature                |                | T <sub>opr</sub> | T <sub>opr</sub> -40 to +85 |    |  |
| Storage temperature                          |                | T <sub>stg</sub> | -55 to +125                 | °C |  |





Note) \*1: Value of each diode in double diodes used.

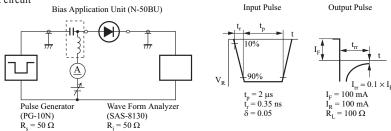
#### ■ Electrical Characteristics $T_a = 25$ °C±3°C

| Parameter                | Symbol           | Conditions  | Min | Тур | Max  | Unit |
|--------------------------|------------------|---|-----|-----|------|------|
| Forward voltage          | $V_{\mathrm{F}}$ | $I_F = 100 \text{ mA}$  |     |     | 0.55 | V    |
| Reverse current          | $I_R$            | $V_R = 30 \text{ V}$  |     |     | 15   | μΑ   |
| Terminal capacitance     | C <sub>t</sub>   | $V_R = 10 \text{ V}, f = 1 \text{ MHz}$                                 |     | 2   |      | pF   |
| Reverse recovery time *1 | t <sub>rr</sub>  | $I_F = I_R = 100 \text{ mA}, I_{rr} = 0.1 \times I_R, R_L = 100 \Omega$ |     | 0.8 |      | ns   |

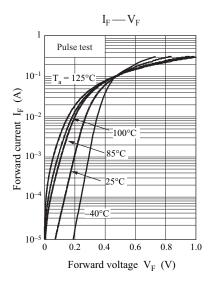
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

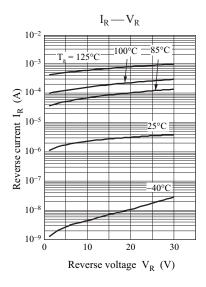
- 2. This product is sensitive to electric shock (static electricity, etc.). Due attention must be paid on the charge of a human body and the leakage of current from the operating equipment.
- 3. Absolute frequency of input and output is 250 MHz

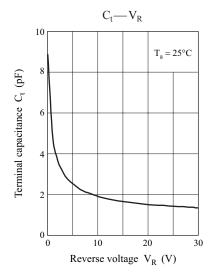
 $*1: t_{rr}$  measurement circuit



<sup>\*2: 50</sup> Hz sine wave 1 cycle (Non-repetitive peak current)



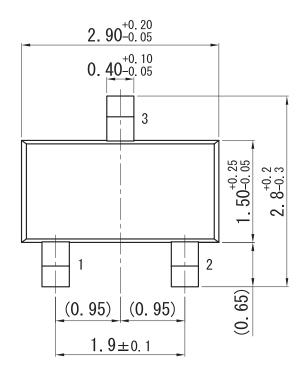


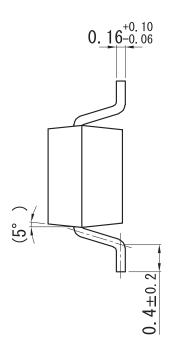


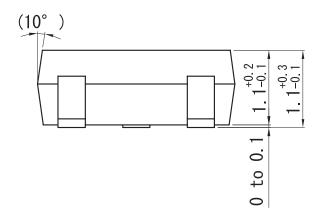
Ver. CED 2

Mini3-G3-B

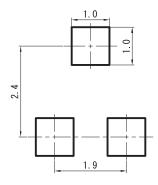
Unit: mm







### ■ Land Pattern (Reference) (Unit: mm)



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